

Special Issue

Additive Manufacturing and Mechanical Properties of Materials

Message from the Guest Editors

This Special Issue provides a comprehensive exploration of the dynamic and evolving field at the confluence of additive manufacturing (AM) and the mechanical properties of materials. It serves as a platform for researchers, engineers, and practitioners to delve into the latest breakthroughs, research findings, and innovative developments in AM techniques and their direct influence on material properties.

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Message from the Editor-in-Chief

As the world of science becomes ever more specialized, researchers may lose themselves in the deep forest of the ever increasing number of subfields being created. This open access journal Applied Sciences has been started to link these subfields, so researchers can cut through the forest and see the surrounding, or quite distant fields and subfields to help develop his/her own research even further with the aid of this multi-dimensional network.

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